



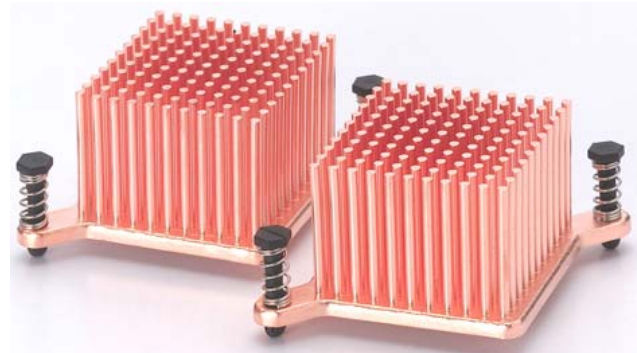
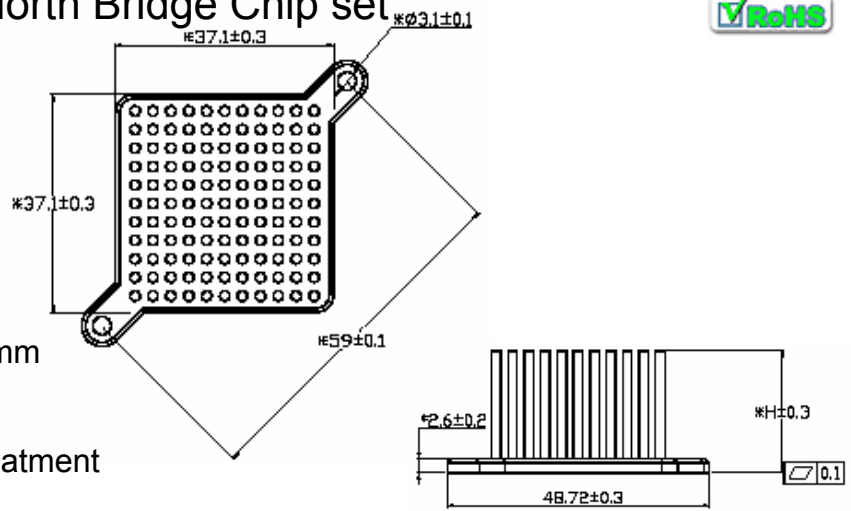
# Model : CMBA054949 Series

## BGA Heat Sink Specification

For North Bridge Chip set



- 1. Material : CU1100
- 2. Dimension :  
 Foot print : 37.5x37.5mm  
 Height : 12,15,18,21,23,28,33 mm  
 Base (thickness) : 2.6mm
- 3. Finish: Antioxidant Treatment
- 4. Accessory :  
 Push Pin : Plastic (UL94-V0)  
 Thermal pad : T725 or others



## Performance

Heat Source (LxW)	15x15
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